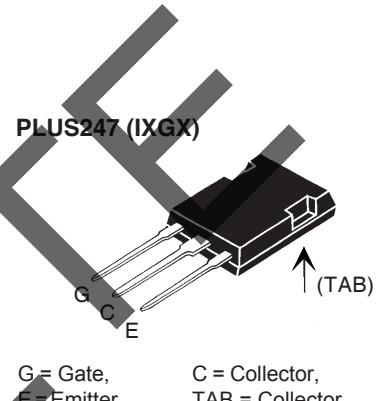
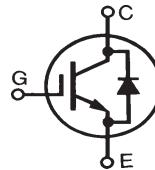


# High Voltage IGBT with Diode

## IXGX 32N170H1

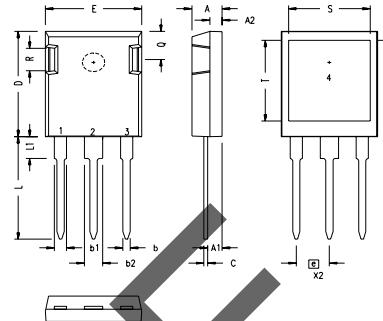
$V_{CES}$	= 1700	V
$I_{C25}$	= 75	A
$V_{CE(sat)}$	= 3.3	V
$t_{fi(ty)}$	= 290	ns



Symbol	Test Conditions	Maximum Ratings		
$V_{CES}$	$T_J = 25^\circ\text{C}$ to $150^\circ\text{C}$	1700	V	
$V_{CGR}$	$T_J = 25^\circ\text{C}$ to $150^\circ\text{C}$ ; $R_{GE} = 1 \text{ M}\Omega$	1700	V	
$V_{GES}$	Continuous	$\pm 20$	V	
$V_{GEM}$	Transient	$\pm 30$	V	
$I_{C25}$	$T_c = 25^\circ\text{C}$	75	A	
$I_{C90}$	$T_c = 90^\circ\text{C}$	32	A	
$I_{CM}$	$T_c = 25^\circ\text{C}$ , 1 ms	200	A	
<b>SSOA (RBSOA)</b>	$V_{GE} = 15 \text{ V}$ , $T_{vj} = 125^\circ\text{C}$ , $R_g = 5\Omega$ Clamped inductive load	$I_{CM} = 90$ @ $0.8 V_{CES}$	A	
$t_{sc}$	$T_J = 125^\circ\text{C}$ , $V_{CE} = 1200 \text{ V}$ ; $V_{GE} = 15 \text{ V}$ , $R_g = 10\Omega$	10	$\mu\text{s}$	
$P_c$	$T_c = 25^\circ\text{C}$	350	W	
$T_J$		-55 ... +150	$^\circ\text{C}$	
$T_{JM}$		150	$^\circ\text{C}$	
$T_{stg}$		-55 ... +150	$^\circ\text{C}$	
$F_c$	Mounting force with chip	22...130/5...30	N/lb	
Maximum lead temperature for soldering 1.6 mm (0.062 in.) from case for 10 s		300	$^\circ\text{C}$	
<b>Weight</b>		6	g	

Symbol	Test Conditions	Characteristic Values ( $T_J = 25^\circ\text{C}$ , unless otherwise specified)			
		min.	typ.	max.	
$BV_{CES}$	$I_c = 1\text{mA}$ , $V_{GE} = 0 \text{ V}$	1700		V	
$V_{GE(th)}$	$I_c = 250 \mu\text{A}$ , $V_{CE} = V_{GE}$	3.0	5.0	V	
$I_{CES}$	$V_{CE} = 0.8 \cdot V_{CES}$ $V_{GE} = 0 \text{ V}$	$T_J = 25^\circ\text{C}$ Note 1 $T_J = 125^\circ\text{C}$	500	$\mu\text{A}$	
			8	mA	
$I_{GES}$	$V_{CE} = 0 \text{ V}$ , $V_{GE} = \pm 20 \text{ V}$		$\pm 100$	nA	
$V_{CE(sat)}$	$I_c = I_{C90}$ , $V_{GE} = 15 \text{ V}$	$T_J = 25^\circ\text{C}$ $T_J = 125^\circ\text{C}$	2.5	3.3	V
			3.0		V

Symbol	Test Conditions	Characteristic Values			
		( $T_J = 25^\circ\text{C}$ , unless otherwise specified)	min.	typ.	max.
$g_{fs}$	$I_C = I_{C25}$ , $V_{CE} = 10\text{ V}$ Note 2	25	33	S	
$C_{ies}$		3500		pF	
$C_{oes}$	$V_{CE} = 25\text{ V}$ , $V_{GE} = 0\text{ V}$ , $f = 1\text{ MHz}$	250		pF	
$C_{res}$		40		pF	
$Q_g$		155		nC	
$Q_{ge}$	$I_C = I_{C90}$ , $V_{GE} = 15\text{ V}$ , $V_{CE} = 0.5 V_{CES}$	30		nC	
$Q_{gc}$		51		nC	
$t_{d(on)}$	<b>Inductive load, <math>T_J = 25^\circ\text{C}</math></b>		45	ns	
$t_{ri}$	$I_C = I_{C90}$ , $V_{GE} = 15\text{ V}$	38	ns		
$t_{d(off)}$	$R_G = 2.7\text{ }\Omega$ , $V_{CE} = 0.8 V_{CES}$ Note 3	270	500	ns	
$t_{fi}$		250	500	ns	
$E_{off}$		15	25	mJ	
$t_{d(on)}$	<b>Inductive load, <math>T_J = 125^\circ\text{C}</math></b>		48	ns	
$t_{ri}$	$I_C = I_{C90}$ , $V_{GE} = 15\text{ V}$	42	ns		
$E_{on}$	$R_G = 2.7\text{ }\Omega$ , $V_{CE} = 0.8 V_{CES}$ Note 3	6.0		mJ	
$t_{d(off)}$		360	ns		
$t_{fi}$		560	ns		
$E_{off}$		22		mJ	
$R_{thJC}$			0.35	K/W	
$R_{thCK}$		0.15		K/W	

**PLUS247 Outline (IXGX)**


SYM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	.190	.205	.483	.521
A1	.090	.100	.229	.254
A2	.075	.085	.191	.216
b	.045	.055	.114	.140
b1	.075	.084	.191	.213
b2	.115	.123	.292	.312
C	.024	.031	.061	.080
D	.819	.840	.2080	.2134
E	.620	.635	.1575	.1613
e	.215 BSC	.215 BSC	.545 BSC	
L	.780	.800	.1981	.2032
L1	.150	.170	.381	.432
Q	.220	.244	.559	.620
R	.170	.190	.432	.483
S	.520	.540	.1321	.1372
T	.620	.640	.1575	.1626
U	.065	.080	.165	.203

1 – GATE  
2 – DRAIN (COLLECTOR)  
3 – SOURCE (EMITTER)  
4 – NO CONNECTION

NOTE: This drawing will meet all dimensions requirement of JEDEC outline TO-247AD except screw hole.

**Reverse Diode (FRED) (Note 4)**

Symbol	Test Conditions	Characteristic Values			
		( $T_J = 25^\circ\text{C}$ , unless otherwise specified)	min.	typ.	max.
$V_F$	$I_F = 70\text{ A}$ , $V_{GE} = 0\text{ V}$ , Pulse test, $t \leq 300\text{ }\mu\text{s}$ , duty cycle $\leq 2\%$		2.7	V	
$I_{RM}$	$I_F = 50\text{ A}$ , $V_{GE} = 0\text{ V}$ , $-di_F/dt = 800\text{ A}/\mu\text{s}$	50		A	
$t_{rr}$	$V_R = 600\text{ V}$	150		ns	
$R_{thJC}$			0.4	K/W	

Notes: 1. Device must be heatsunk for high temperature leakage current measurements to avoid thermal runaway.

1. Pulse test,  $t \leq 300\text{ }\mu\text{s}$ , duty cycle  $\leq 2\%$
2. Switching times may increase for  $V_{CE}$  (Clamp)  $> 0.8 \cdot V_{CES}$ , higher  $T_J$  or increased  $R_G$ .
3. See DH60-18A and IXGH32N170A datasheets for additional characteristics

IXYS reserves the right to change limits, test conditions, and dimensions.

IXYS MOSFETs and IGBTs are covered by one or more of the following U.S. patents: 4,835,592 4,881,106 5,017,508 5,049,961 5,187,117 5,486,715 6,306,728B1 6,259,123B1 6,306,728B1 4,850,072 4,931,844 5,034,796 5,063,307 5,237,481 5,381,025 6,404,065B1 6,162,665 6,534,343



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